



Application No. 10/690,875
Amendment dated August 25, 2006
Reply to Office Action of May 26, 2006

Docket No.: 0951-0127P

AMENDMENTS TO THE CLAIMS

1. (Original) A leadframe to be used in a semiconductor device,
which comprises a plurality of parallel first leads and a plurality of parallel second leads,
wherein the pitch of the first leads is different from that of the second leads, the pitch of the first leads corresponds to a pitch of terminals of a surface mount-type electronic device and the pitch of the second leads corresponds to a pitch of terminals of a through hole mount-type electronic device, and the first leads are joined end-to-end with the second leads.

2. (Original) The leadframe according to claim 1,
wherein at least either of the first leads or the second leads have their thickness reduced.

Claims 3 and 4 (Cancelled).

5. (Original) A semiconductor device using the leadframe according to claim 1.

6. (Original) An electronic equipment using the semiconductor device according to claim 5.

Claims 7-11 (Cancelled).

12. (New) A leadframe for a semiconductor device comprising:
a plurality of parallel first leads each having a first length, a first width and a first thickness and the plurality of first leads having a first pitch corresponding to a pitch of terminals of a surface mount-type electronic device; and

a plurality of parallel second leads each having a second length, a second width, a second thickness and a second pitch corresponding to a pitch of terminals of a through hole mount-type electronic device;

wherein the first leads are joined end to end with the second leads; and

wherein said first pitch is different from said second pitch and said first thickness is less

than said second thickness.

13. (New) A semiconductor device comprising the leadframe of claim 12.

14. (New) An electronic equipment comprising the semiconductor device according to claim 13.

15. (New) A leadframe for a semiconductor device comprising:

a plurality of parallel first leads arranged in a plane, each of the first leads having a first thickness in a direction normal to the plane and the plurality of first leads having a first pitch corresponding to a pitch of terminals of a surface mount-type electronic device; and

a plurality of parallel second leads arranged in the plane, each of the second leads having a second thickness in the direction normal to the plane less than said first thickness and the plurality of second leads having a second pitch corresponding to a pitch of terminals of a through hole mount-type electronic device and different than said first pitch;

wherein the first leads are joined end to end with the second leads.

16. (New) A semiconductor device comprising the leadframe of claim 15.

17. (New) An electronic equipment comprising the semiconductor device according to claim 16.